

## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

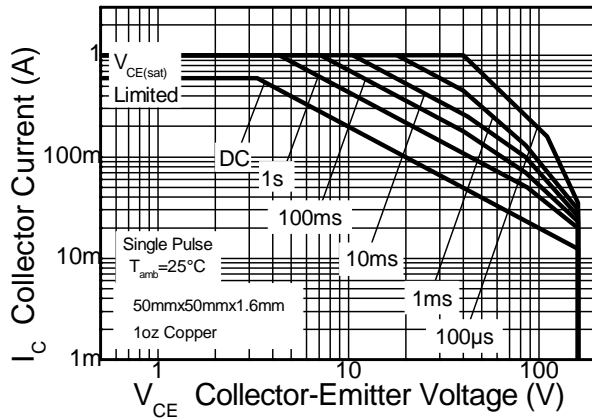
Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	180	V
Collector-Emitter Voltage	V <sub>CEO</sub>	160	V
Emitter-Base Voltage	V <sub>EBO</sub>	6	V
Continuous Collector Current	I <sub>C</sub>	600	mA
Peak Collector Current	I <sub>CM</sub>	1	A

## Thermal Characteristics

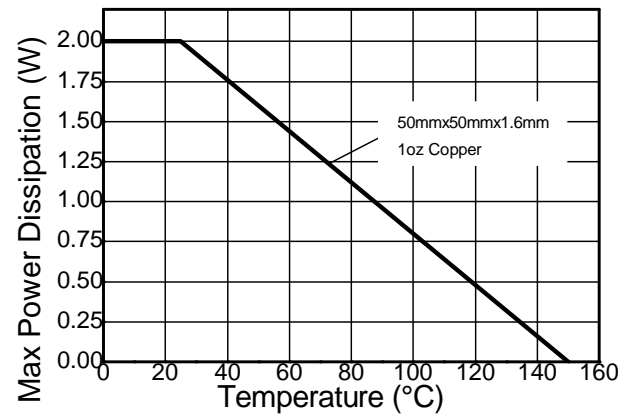
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	2	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	62.5	°C/W
Thermal Resistance, Junction to Leads (Note 6)	R <sub>θJL</sub>	34.05	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes: 5. Device mounted on 50mm X 50mm X 1.6mm FR-4 PCB with high coverage of single sided 1 oz. copper, in still air condition  
6. Thermal resistance from junction to solder-point (at the end of the collector lead).

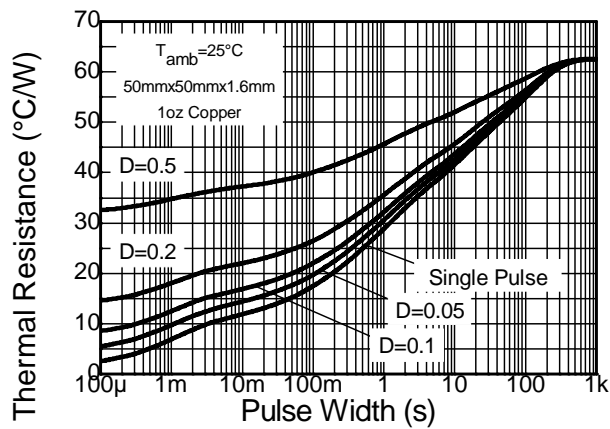
## Thermal Characteristics and Derating Information



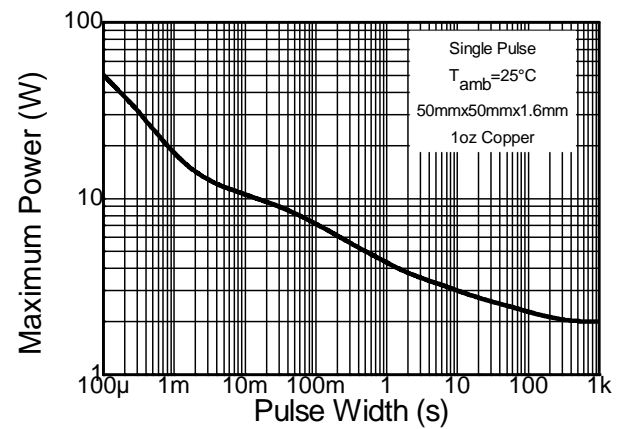
**Safe Operating Area**



**Derating Curve**



**Transient Thermal Impedance**



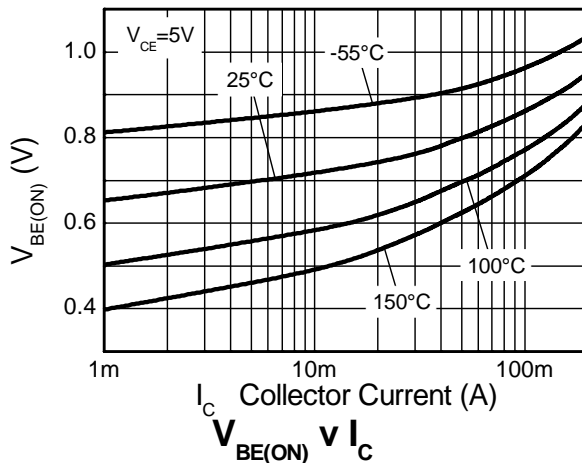
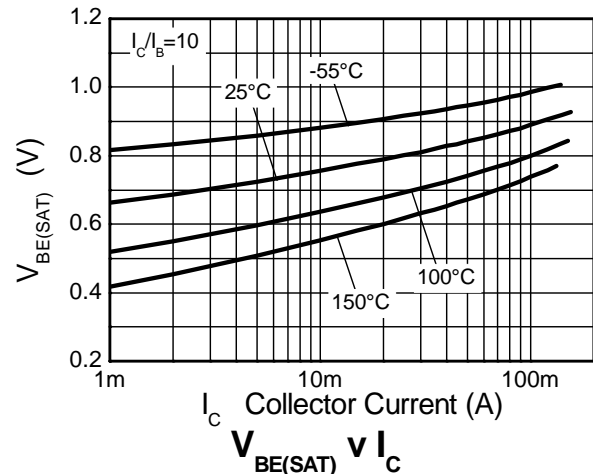
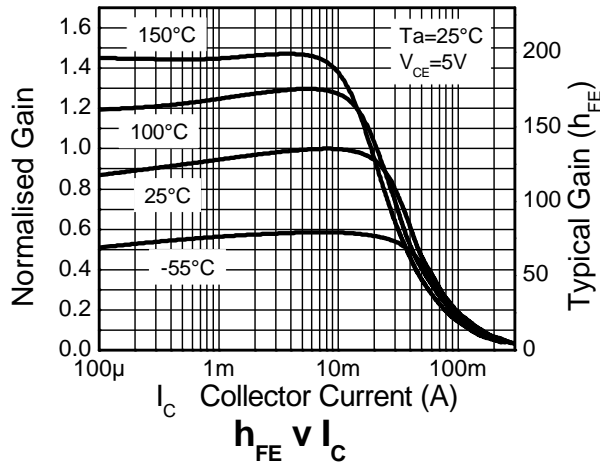
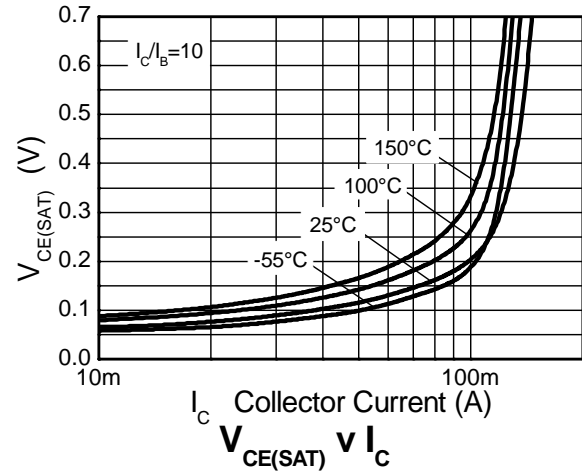
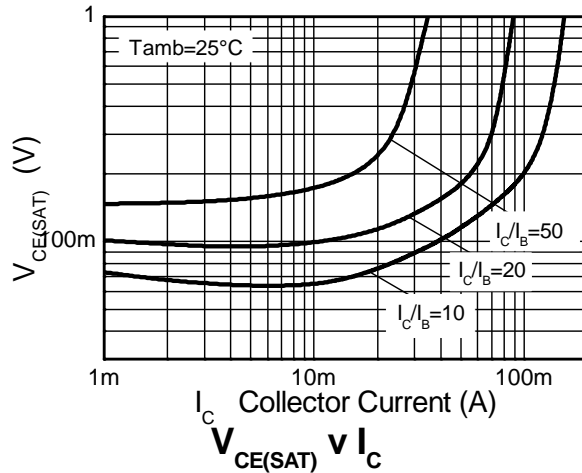
**Pulse Power Dissipation**

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	180	270	—	V	I <sub>C</sub> = 100μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage (Note 7)	BV <sub>CEO</sub>	160	200	—	V	I <sub>C</sub> = 1mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	6.0	7.85	—	V	I <sub>E</sub> = 100μA, I <sub>C</sub> = 0
Collector Cutoff Current	I <sub>CBO</sub>	—	<1	50	nA	V <sub>CB</sub> = 120V, I <sub>E</sub> = 0
Emitter Cutoff Current	I <sub>EBO</sub>	—	<1	50	μA	V <sub>CB</sub> = 120V, I <sub>E</sub> = 0, T <sub>A</sub> = +100°C
						V <sub>EB</sub> = 4V, I <sub>C</sub> = 0
<b>ON CHARACTERISTICS (Note 7)</b>						
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	—	65 115	150 200	mV mV	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1mA I <sub>C</sub> = 50mA, I <sub>B</sub> = 5mA
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	—	760 840	1000 1200	mV mV	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1mA I <sub>C</sub> = 50mA, I <sub>B</sub> = 5mA
DC Current Gain	h <sub>FE</sub>	80 80 30	130 145 65	— 250 —	—	I <sub>C</sub> = 1mA, V <sub>CE</sub> = 5V I <sub>C</sub> = 10mA, V <sub>CE</sub> = 5V I <sub>C</sub> = 50mA, V <sub>CE</sub> = 5V
<b>SMALL SIGNAL CHARACTERISTICS</b>						
Transition Frequency	f <sub>T</sub>	100	130	300	MHz	V <sub>CE</sub> = 10V, I <sub>C</sub> = 10mA, f = 100MHz
Small Signal Current Gain	h <sub>fe</sub>	50	—	260	—	V <sub>CE</sub> = 10V, I <sub>C</sub> = 10mA, f = 1kHz
Output Capacitance	C <sub>obo</sub>	—	—	6	pF	V <sub>CB</sub> = 10V, f = 1MHz
Noise Figure	NF	—	—	8	dB	V <sub>CE</sub> = 5.0V, I <sub>C</sub> = 200μA, R <sub>S</sub> = 1.0kΩ, f = 1.0kHz
Delay Time	t <sub>(d)</sub>	—	95	—	ns	V <sub>CC</sub> = 10V, I <sub>C</sub> = 10mA, I <sub>B1</sub> = -I <sub>B2</sub> = 1mA
Rise Time	t <sub>(r)</sub>	—	64	—	ns	
Storage Time	t <sub>(s)</sub>	—	1256	—	ns	
Delay Time	t <sub>(f)</sub>	—	140	—	ns	

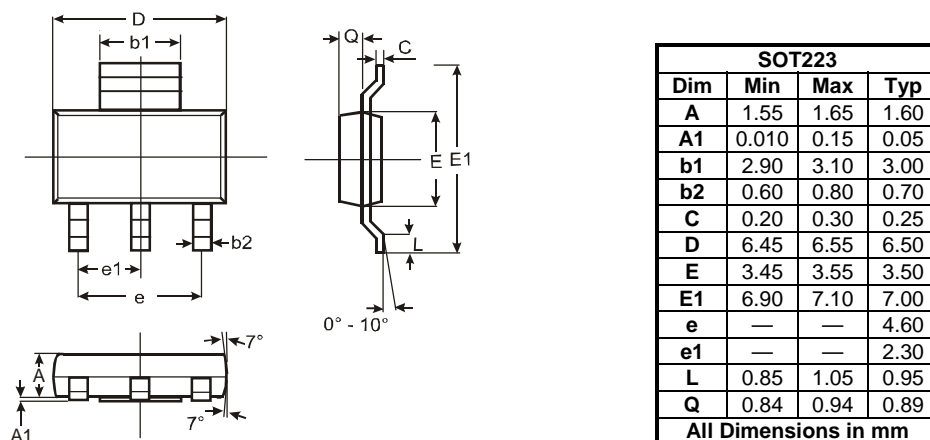
Notes: 7. Pulse Test: Pulse width ≤ 300μs. Duty cycle ≤ 2.0%.

**Typical Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)



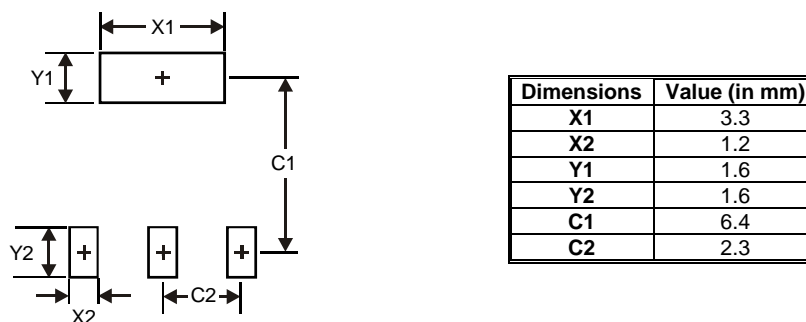
## Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



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